

PLATING APPARATUS

ABSTRACT

A plating apparatus including a plating bath, a substrate holder to be arranged in the plating bath and adapted to hold a substrate, an anode for generating an electric field between the substrate and the anode, and at least one electric field shielding body for shielding the substrate holder and a part or the whole of the electric field, wherein the electric field shielding body has an opening portion for allowing the electric field between the substrate and the anode to pass therethrough, and is configured so as to be capable of adjusting an opening size in a first direction of the opening portion and an opening size in a second direction of the opening portion independently of each other.

Representative drawing: Fig. 3